# **CBT3126**

# Quad FET bus switch Rev. 04 — 12 October 2009

**Product data sheet** 

#### **General description** 1.

The CBT3126 is a quad FET bus switch with independent line switches. Each switch is disabled when the associated Output Enable (OE) input is LOW.

The CBT3126 is characterized for operation from -40 °C to +85 °C.

#### 2. **Features**

- Standard '126-type pinout
- Multiple package options
- $\blacksquare$  5  $\Omega$  switch connection between two ports
- TTL-compatible input levels
- Minimal propagation delay through the switch
- Latch-up protection exceeds 500 mA per JEDEC standard JESD78 class II level A
- ESD protection:
  - ◆ HBM JESD22-A114E exceeds 2000 V
  - MM JESD22-A115-A exceeds 200 V
  - CDM JESD22-C101C exceeds 1000 V
- Specified from -40 °C to +85 °C

#### **Ordering information** 3.

Table 1. **Ordering information** 

Type number	Temperature range	Package							
		Name	Description	Version					
CBT3126D	–40 °C to +85 °C	SO14	plastic small outline package; 14 leads; body width 3.9 mm	SOT108-1					
CBT3126DB	–40 °C to +85 °C	SSOP14	plastic shrink small outline package; 14 leads; body width 5.3 mm	SOT337-1					
CBT3126PW	–40 °C to +85 °C	TSSOP14	plastic thin shrink small outline package; 14 leads; body width 4.4 mm	SOT402-1					
CBT3126DS	–40 °C to +85 °C	SSOP16[1]	plastic shrink small outline package; 16 leads; body width 3.9 mm; lead pitch 0.635 mm	SOT519-1					

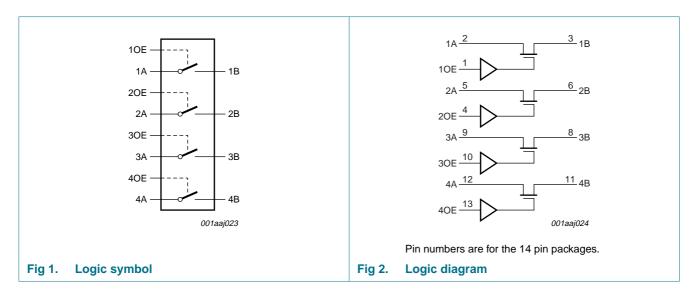
[1] Also known as QSOP16.



**Quad FET bus switch** 

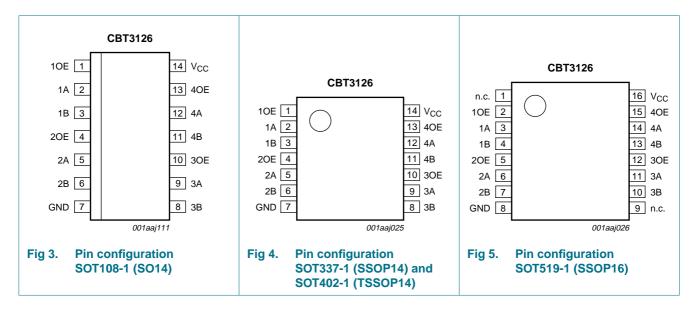
2 of 13

## **Functional diagram**



#### **Pinning information 5**.

## 5.1 Pinning



### 5.2 Pin description

Table 2 Pin description

Table 2. This decompliant									
Symbol	Pin	Description							
	SOT108-1 SOT337-1 and SOT402-1	SOT519-1							
10E to 40E	1, 4, 10, 13	2, 5, 12, 15	output enable input						
1A to 4A,	2, 5, 9, 12	3, 6, 11, 14	A input/output						
1B to 4B	3, 6, 8, 11	4, 7, 10, 13	B output/input						

© NXP B.V. 2009. All rights reserved. Rev. 04 — 12 October 2009

**Quad FET bus switch** 

 Table 2.
 Pin description ...continued

Symbol	Pin		Description			
	SOT108-1 SOT337-1 and SOT402-1	SOT519-1				
GND	7	8	ground (0 V)			
V <sub>CC</sub>	14	16	positive supply voltage			
n.c.	-	1, 9	not connected			

# 6. Functional description

#### Table 3. Function selection

 $H = HIGH \ voltage \ level; \ L = LOW \ voltage \ level.$ 

Inputs	Switch
nOE	
L	nA to nB disconnected
Н	nA to nB connected

## 7. Limiting values

#### Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		-0.5	+7.0	V
$V_{I}$	input voltage		[ <u>1</u> ] -0.5	+7.0	V
$I_{\text{SW}}$	switch current	continuous current through each switch	-	128	mA
$I_{IK}$	input clamping current	$V_I < 0 V$	-50	-	mA
$T_{stg}$	storage temperature		-65	+150	°C
$P_{tot}$	total power dissipation	$T_{amb} = -40  ^{\circ}\text{C} \text{ to } +125  ^{\circ}\text{C}$	[2]		
		SO14 package	<u>[3]</u> _	500	mW
		SSOP14 and SSOP16 package	<u>[4]</u> _	500	mW
		TSSOP14 package	<u>[4]</u> _	500	mW

<sup>[1]</sup> The input and output negative voltage ratings may be exceeded if the input and output clamp current ratings are observed.

# 8. Recommended operating conditions

#### Table 5. Operating conditions

All unused control inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation.

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		4.5	5.5	V
$V_{IH}$	HIGH-level input voltage		2.0	-	V
$V_{IL}$	LOW-level input voltage		-	0.8	V
T <sub>amb</sub>	ambient temperature	operating in free-air	-40	+85	°C

CBT3126\_4 © NXP B.V. 2009. All rights reserved.

<sup>[2]</sup> The package thermal impedance is calculated from JESD51-7.

<sup>[3]</sup> For SO14 package;  $P_{tot}$  derates linearly with 8 mW/K above 70 °C.

<sup>[4]</sup> For SSOP14, SSOP16 and TSSOP14 packages;  $P_{tot}$  derates linearly with 5.5 mW/K above 70 °C.

**Quad FET bus switch** 

### 9. Static characteristics

Table 6. Static characteristics

 $T_{amb}$  = -40 °C to +85 °C.

· amb						
Symbol	Parameter	Conditions	Min	Typ[1]	Max	Unit
$V_{\text{IK}}$	input clamping voltage	$V_{CC} = 4.5 \text{ V}; I_I = -18 \text{ mA}$	-	-	-1.2	V
$V_{pass}$	pass voltage	$V_{I}$ = $V_{CC}$ = 5.0 V; $I_{SW}$ = $-100~\mu A$	-	3.8	-	V
I <sub>I</sub>	input leakage current	$V_{CC}$ = 5.5 V; $V_I$ = GND or 5.5 V	-	-	±1	μΑ
I <sub>CC</sub>	supply current	$V_{CC}$ = 5.5 V; $I_{SW}$ = 0 mA; $V_I$ = $V_{CC}$ or GND	-	-	3	μΑ
$\Delta I_{CC}$	additional supply current	control pins; per input; $V_{CC} = 5.5 \text{ V}$ ; one input at 3.4 V, other inputs at $V_{CC}$ or GND	[2] -	-	2.5	mA
C <sub>I</sub>	input capacitance	control pins; V <sub>I</sub> = 3 V or 0 V	-	1.7	-	pF
$C_{io(off)}$	off-state input/output capacitance	$V_O = 3 \text{ V or } 0 \text{ V}; \text{ nOE} = V_{CC}$	-	3.4	-	pF
R <sub>ON</sub>	ON resistance	$V_{CC} = 4.0 \text{ V}$	[3]			
		$V_I = 2.4 \text{ V}; I_I = 15 \text{ mA}$	-	16	22	Ω
		V <sub>CC</sub> = 4.5 V				
		$V_I = 0 \ V; \ I_I = 64 \ mA$	-	5	7	Ω
		$V_I = 0 \ V; \ I_I = 30 \ mA$	-	5	7	Ω
		$V_I = 2.4 \text{ V}; I_I = 15 \text{ mA}$	-	10	15	Ω

<sup>[1]</sup> All typical values are measured at  $V_{CC}$  = 5 V;  $T_{amb}$  = 25 °C.

## 10. Dynamic characteristics

Table 7. Dynamic characteristics

 $T_{amb}$  = -40 °C to +85 °C;  $V_{CC}$  = 4.5 V to 5.5 V; for test circuit see Figure 8.

Symbol	Parameter	Conditions	Min	Max	Unit
$t_{pd}$	propagation delay	nA to nB or nB to nA; see Figure 6	[1][2]	0.25	ns
t <sub>en</sub>	enable time	nOE to nA or nB; see Figure 7	<sup>[2]</sup> 1.6	4.5	ns
t <sub>dis</sub>	disable time	nOE to nA or nB; see Figure 7	[ <u>2</u> ] 1.0	5.4	ns

<sup>[1]</sup> This parameter is warranted but not production tested. The propagation delay is based on the RC time constant of the typical ON resistance of the switch and a load capacitance, when driven by an ideal voltage source (zero output impedance).

[2]  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ ;  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ ;  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .

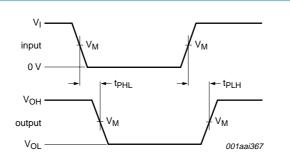
© NXP B.V. 2009. All rights reserved.

<sup>[2]</sup> This is the increase in supply current for each input that is at the specified TTL voltage level rather than  $V_{CC}$  or GND.

<sup>[3]</sup> Measured by the voltage drop between the A and the B terminals at the indicated current through the switch. ON resistance is determined by the lowest voltage of the two (A or B) terminals.

**Quad FET bus switch** 

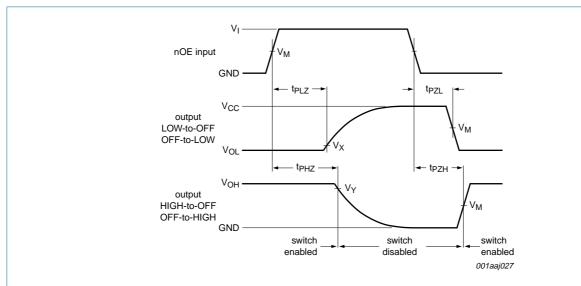
## 11. AC waveforms



Measurement points are given in Table 8.

 $V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

The input (nA, nB) to output (nB, nA) propagation delay times Fig 6.



Measurement points are given in Table 8.

 $V_{\text{OL}}$  and  $V_{\text{OH}}$  are typical voltage output levels that occur with the output load.

Fig 7. **Enable and disable times** 

Table 8. **Measurement points** 

Input	Output		
V <sub>M</sub>	V <sub>M</sub>	V <sub>X</sub>	V <sub>Y</sub>
1.5 V	1.5 V	V <sub>OL</sub> + 0.3 V	V <sub>OH</sub> – 0.3 V

CBT3126\_4 Rev. 04 — 12 October 2009

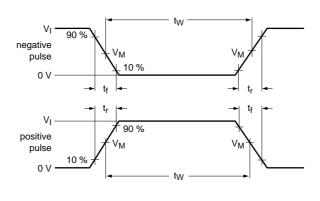
**Product data sheet** 

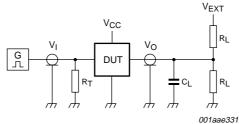
5 of 13

**Quad FET bus switch** 

6 of 13

## 12. Test information





Test data is given in Table 9.

Definitions for test circuit:

R<sub>L</sub> = Load resistance.

 $C_L$  = Load capacitance including jig and probe capacitance.

 $R_T$  = Termination resistance should be equal to the output impedance  $Z_0$  of the pulse generator.

 $V_{\text{EXT}}$  = External voltage for measuring switching times.

Test circuit for measuring switching times Fig 8.

Table 9. **Test data** 

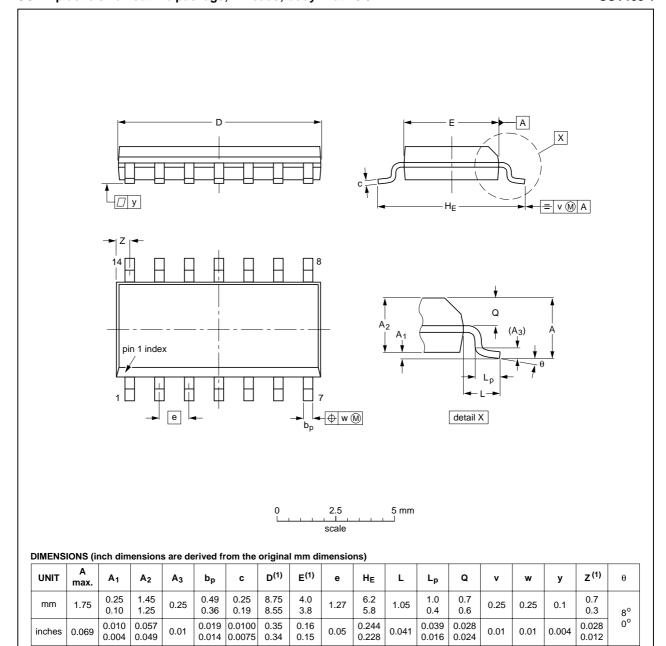
Supply voltage	Input		Load	Load		V <sub>EXT</sub>			
V <sub>CC</sub>	V <sub>I</sub> t <sub>r</sub> , t <sub>f</sub>		CL	R <sub>L</sub>	t <sub>PLH</sub> , t <sub>PHL</sub>	t <sub>PLZ</sub> , t <sub>PZL</sub>	t <sub>PHZ</sub> , t <sub>PZH</sub>		
4.5 V to 5.5 V	GND to 3.0 V ≤ 2.5 ns 5		50 pF 500 Ω		open	7.0 V	open		

#### **Quad FET bus switch**

# 13. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1



#### Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE	ERSION IEC JEDEC	ENCES		EUROPEAN	ISSUE DATE	
VERSION IEC		JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT108-1	076E06	MS-012				<del>99-12-27</del> 03-02-19

Fig 9. Package outline SOT108-1 (SO14)

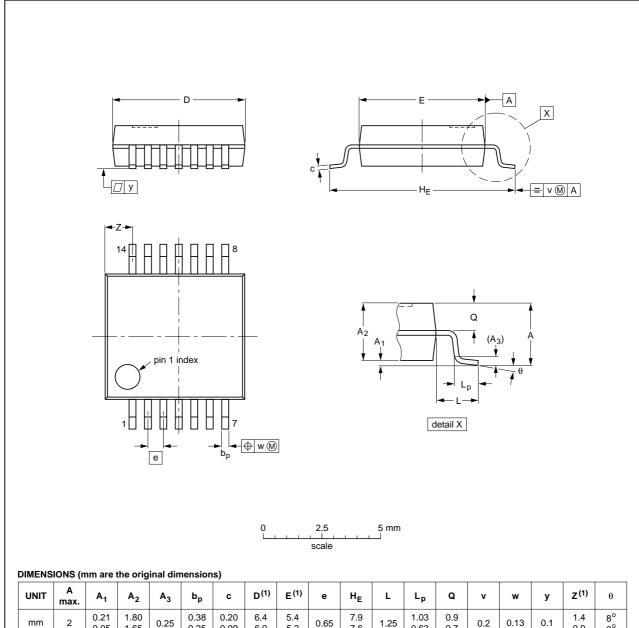
CBT3126\_4 © NXP B.V. 2009. All rights reserved.

**Quad FET bus switch** 

SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1

8 of 13



Dimerio	Similar of the Critiques and original authoritions,																	
UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	bp	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	HE	L	Lp	Q	v	w	у	Z <sup>(1)</sup>	θ
mm	2	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	6.4 6.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	1.4 0.9	8° 0°

#### Note

**Product data sheet** 

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

	OUTLINE		REFER	EUROPEAN	ISSUE DATE		
	VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
	SOT337-1		MO-150				<del>99-12-27</del> 03-02-19
_							

Fig 10. Package outline SOT337-1 (SSOP14)

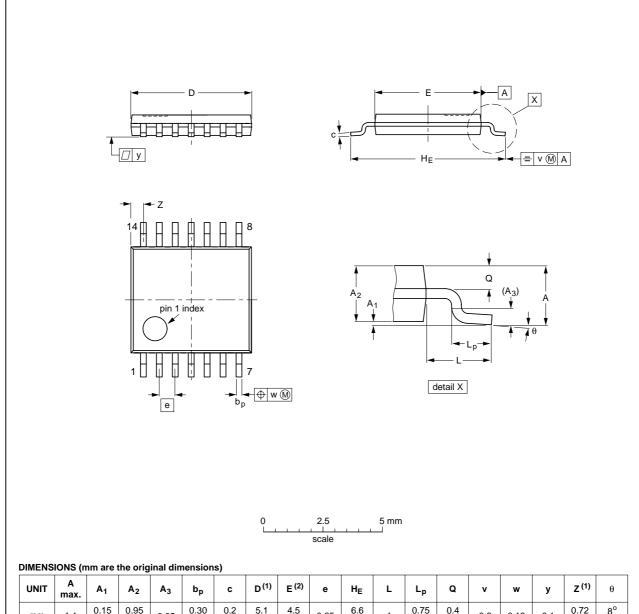
CBT3126\_4 © NXP B.V. 2009. All rights reserved. Rev. 04 — 12 October 2009

**Quad FET bus switch** 

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1

9 of 13



U	TIN	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	bp	С	D <sup>(1)</sup>	E (2)	е	HE	L	Lp	Q	v	w	у	Z <sup>(1)</sup>	θ
m	nm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.72 0.38	8° 0°

**Product data sheet** 

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT402-1		MO-153				<del>99-12-27</del> 03-02-18
	•	•				

Fig 11. Package outline SOT402-1 (TSSOP14)

© NXP B.V. 2009. All rights reserved. Rev. 04 — 12 October 2009

**Quad FET bus switch** 

10 of 13

SSOP16: plastic shrink small outline package; 16 leads; body width 3.9 mm; lead pitch 0.635 mm SOT519-1

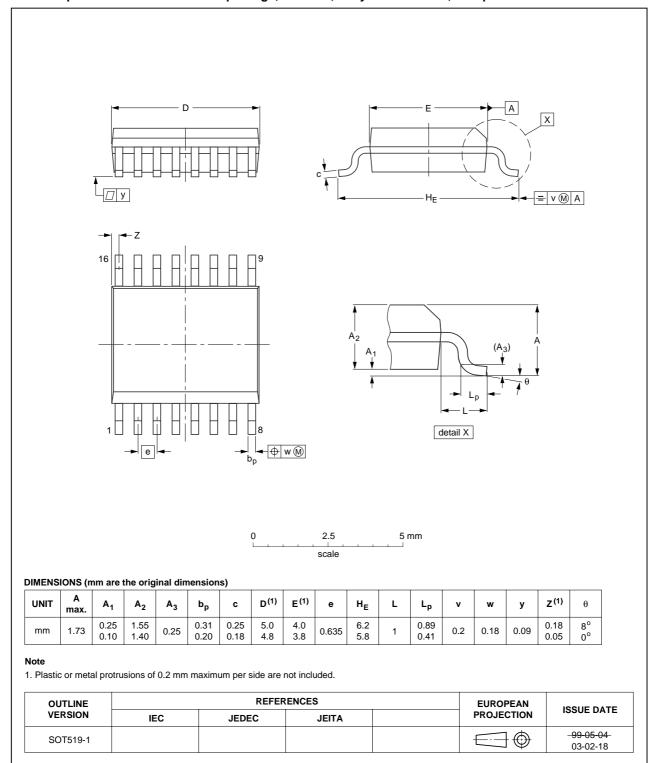


Fig 12. Package outline SOT519-1 (SSOP16)

CBT3126\_4 © NXP B.V. 2009. All rights reserved. Rev. 04 — 12 October 2009

**Quad FET bus switch** 

## 14. Abbreviations

#### Table 10. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
НВМ	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

# 15. Revision history

### Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
CBT3126_4	20091012	Product data sheet	-	CBT3126_3
Modifications:	<ul> <li>Section 7 "Lir</li> </ul>	niting values" changed I <sub>CC</sub> to I <sub>S</sub>	sw-	
CBT3126_3	20081209	Product data sheet	-	CBT3126_2
CBT3126_2	20081023	Product data sheet	-	CBT3126_1
CBT3126_1	20011212	Product data sheet	-	-

Quad FET bus switch

## 16. Legal information

#### 16.1 **Data sheet status**

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- Please consult the most recently issued document before initiating or completing a design.
- The term 'short data sheet' is explained in section "Definitions'
- The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

#### 16.2 Definitions

Draft — The document is a draft version only. The content is still under internal review and subject to formal approval, which may result in modifications or additions. NXP Semiconductors does not give any representations or warranties as to the accuracy or completeness of information included herein and shall have no liability for the consequences of use of such information.

Short data sheet — A short data sheet is an extract from a full data sheet with the same product type number(s) and title. A short data sheet is intended for quick reference only and should not be relied upon to contain detailed and full information. For detailed and full information see the relevant full data sheet, which is available on request via the local NXP Semiconductors sales office. In case of any inconsistency or conflict with the short data sheet, the full data sheet shall prevail.

#### 16.3 **Disclaimers**

General — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Suitability for use — NXP Semiconductors products are not designed, authorized or warranted to be suitable for use in medical, military, aircraft, space or life support equipment, nor in applications where failure or malfunction of an NXP Semiconductors product can reasonably be expected to result in personal injury, death or severe property or environmental

damage. NXP Semiconductors accepts no liability for inclusion and/or use of NXP Semiconductors products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

**Applications** — Applications that are described herein for any of these products are for illustrative purposes only. NXP Semiconductors makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Limiting values — Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) may cause permanent damage to the device. Limiting values are stress ratings only and operation of the device at these or any other conditions above those given in the Characteristics sections of this document is not implied. Exposure to limiting values for extended periods may affect device reliability.

Terms and conditions of sale — NXP Semiconductors products are sold subject to the general terms and conditions of commercial sale, as published at http://www.nxp.com/profile/terms, including those pertaining to warranty, intellectual property rights infringement and limitation of liability, unless explicitly otherwise agreed to in writing by NXP Semiconductors. In case of any inconsistency or conflict between information in this document and such terms and conditions, the latter will prevail.

No offer to sell or license — Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.

Export control — This document as well as the item(s) described herein may be subject to export control regulations. Export might require a prior authorization from national authorities.

### 16.4 Trademarks

Notice: All referenced brands, product names, service names and trademarks are the property of their respective owners.

12 of 13

#### 17. Contact information

For more information, please visit: http://www.nxp.com

For sales office addresses, please send an email to: salesaddresses@nxp.com

© NXP B.V. 2009. All rights reserved.

#### **Quad FET bus switch**

## 18. Contents

1	General description
2	Features
3	Ordering information
4	Functional diagram 2
5	Pinning information 2
5.1	Pinning
5.2	Pin description
6	Functional description 3
7	Limiting values 3
8	Recommended operating conditions 3
9	Static characteristics 4
10	Dynamic characteristics 4
11	AC waveforms 5
12	Test information 6
13	Package outline
14	Abbreviations11
15	Revision history
16	Legal information
16.1	Data sheet status
16.2	Definitions 12
16.3	Disclaimers
16.4	Trademarks12
17	Contact information 12
18	Contents

Please be aware that important notices concerning this document and the product(s) described herein, have been included in section 'Legal information'.



All rights reserved.

For more information, please visit: http://www.nxp.com For sales office addresses, please send an email to: salesaddresses@nxp.com

Date of release: 12 October 2009 Document identifier: CBT3126\_4

